# Switch-mode Power Rectifier

**DPAK Surface Mount Package** 

# MBRD835L, SBRD8835L

This switch-mode power rectifier which uses the Schottky Barrier principle with a proprietary barrier metal, is designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

#### **Features**

- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Compact Size
- Lead Formed for Surface Mount
- SBRD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 75 Units Per Plastic Tube
- ESD Rating:
  - Machine Model = C (> 400 V)
  - Human Body Model = 3B (> 8000 V)



## ON Semiconductor®

www.onsemi.com

# SCHOTTKY BARRIER RECTIFIER 8.0 AMPERES, 35 VOLTS





#### **MARKING DIAGRAM**



B835LG = Specific Device Number A = Assembly Location\*

Y = Year

WW = Work Week
G = Pb-Free Device

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBRD835LG	DPAK (Pb-Free)	75 Units / Rail
SBRD8835LG	DPAK (Pb-Free)	75 Units / Rail
SBRD8835LG-VF01	DPAK (Pb-Free)	75 Units / Rail
MBRD835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD8835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD8835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure BRD8011/D

<sup>\*</sup> The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

# MBRD835L, SBRD8835L

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	35	V
Average Rectified Forward Current (T <sub>C</sub> = 88°C)	I <sub>F(AV)</sub>	8.0	А
Peak Repetitive Forward Current (Square Wave, Duty = 0.5, T <sub>C</sub> = 80°C)	I <sub>FRM</sub>	16	А
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	75	А
Repetitive Avalanche Current (Current Decaying Linearly to Zero in 1 $\mu$ s, Frequency Limited by $T_{Jmax}$ )	I <sub>AR</sub>	2.0	Α
Storage / Operating Case Temperature	T <sub>stg</sub>	-65 to +150	°C
Operating Junction Temperature (Note 1)	T <sub>J</sub>	-65 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{ heta JC}$	2.8	°C/W
Thermal Resistance – Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	°C/W

<sup>2.</sup> Rating applies when surface mounted on the minimum pad size recommended.

### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 8$ Amps, $T_C = +25^{\circ}C$ ) ( $i_F = 8$ Amps, $T_C = +125^{\circ}C$ )	V <sub>F</sub>	0.51 0.41	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25^{\circ}C$ ) (Rated dc Voltage, $T_C = +100^{\circ}C$ )	I <sub>R</sub>	1.4 35	mA

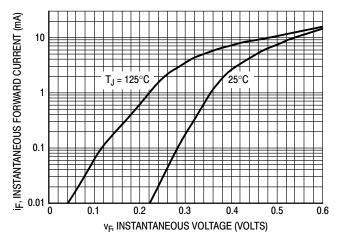
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2%.

# MBRD835L, SBRD8835L

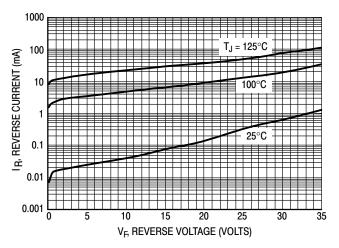
# **TYPICAL CHARACTERISTICS**



10 T<sub>J</sub> = 125°C T<sub></sub>

Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage



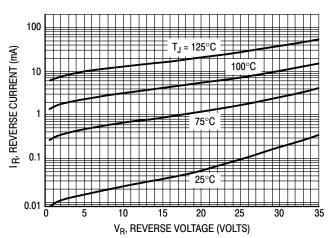


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current

## MBRD835L, SBRD8835L

#### **TYPICAL CHARACTERISTICS**

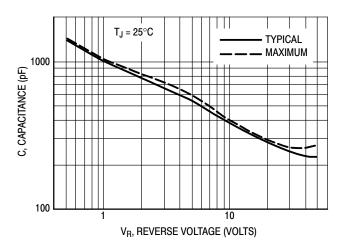


Figure 5. Maximum and Typical Capacitance

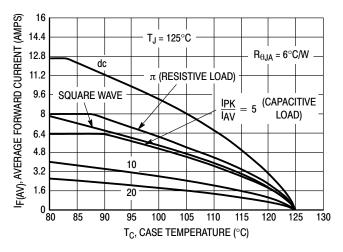


Figure 6. Current Derating, Infinite Heatsink

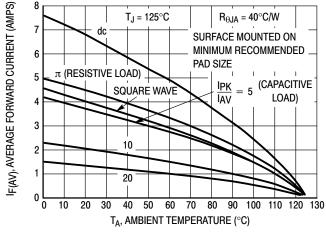


Figure 7. Current Derating

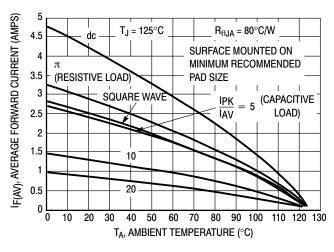


Figure 8. Current Derating, Free Air

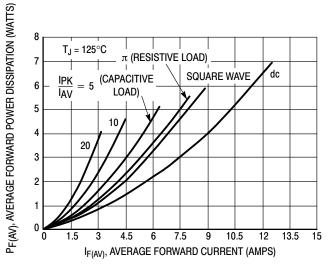


Figure 9. Forward Power Dissipation

В

NOTE 7

|  $\oplus$  | 0.005 (0.13) lacktriangledown C

Ħ

Α1

- h3

Ո

**TOP VIEW** 

L3

b2 e

L2 GAUGE

# **DPAK (SINGLE GAUGE)** CASE 369C **ISSUE F** SCALE 1:1 Α

DETAIL A

C SEATING

C-

SIDE VIEW

**DATE 21 JUL 2015** 

#### NOTES:

z

**BOTTOM VIEW** 

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

#### ALTERNATE CONSTRUCTIONS **DETAIL A** ROTATED 90° CW **GENERIC** STYLE 1: STYLE 2: STYLE 3: STYLE 4: STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE PIN 1. GATE 2. DRAIN

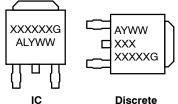
Z

**BOTTOM VIEW** 

С

3. EMITTE 4. COLLE	ER .	3. SOURCE 4. DRAIN	3. ANC 4. CAT	DE	3. GATE 4. ANODE	3.	CATHODE ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE	STYLE 7: PIN 1. GATE 2. COLLE 3. EMITT	ECTOR	E 8: 1. N/C 2. CATHODE 3. ANODE	STYLE 9: PIN 1. ANO 2. CATI 3. RES		2. /	0: CATHODE ANODE CATHODE
4. MT2	4. COLLE		4. CATHODE	4. CAT			ANODE

# **MARKING DIAGRAM\***



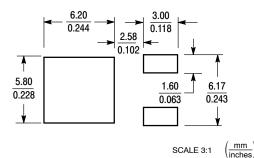
XXXXXX = Device Code = Assembly Location Α L = Wafer Lot Υ = Year WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.

= Pb-Free Package

G

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON10527D	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DPAK (SINGLE GAUGE)		PAGE 1 OF 1	

ON Semiconductor and un are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# onsemi:

<u>SBR835LT4G MBRD835L MBRD835LG MBRD835LT4 MBRD835LT4G SBRD8835LT4G SBRD8835LT4G-VF01 SBRD8835LT4G-VF01 SBRD8835LT4G-VF01</u>